

ABSTRACT

An object of the present invention is to simplify the grounding operation.

5 In wiring board 1 of the present invention, a shield film 50 is connected to a specific wiring member (ground wiring) 17 at the bottoms of openings 14 in cover film 21 and the shield film 50 is wrapped from the side of cover film 21 to the side of base film 11. Therefore, shield film 50 can be placed at ground potential
10 on not only the side of cover film 21 but also the side of base film 11, whereby wiring board 1 can be wholly shielded from the noise emitted from other electronic components. Ground wiring 17 is patterned to be wider than the other wiring members (signal wirings) 18, which allows a large current to pass and openings 14
15 to be made in a large diameter, so that cover film 21 can be easily aligned and more reliably connected to shield film 50.

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